

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ARLYNN W. SMITH	11/21/2017
DAN CHILCOTT	11/21/2017
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16773042
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	2617071-14603 (1)
<b>NAME OF SUBMITTER:</b>	KEVIN T. MCCORMICK
<b>SIGNATURE:</b>	/Kevin T. McCormick/
<b>DATE SIGNED:</b>	01/29/2020
<b>Total Attachments: 1</b>	
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**ASSIGNMENT**

For good and valuable consideration, WE, Arlynn W. SMITH, a U.S. citizen, residing at 208 Stonehaven Lane, Blue Ridge, Virginia 24064; Dan CHILCOTT, a U.S. citizen, residing at 131 Park Vista Drive, Buchanan, Virginia 24066, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Eagle Technology, LLC**, a corporation organized and existing under the laws of the state of Delaware, having a place of business at 1025 W. NASA Boulevard, Melbourne, Florida 32919, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

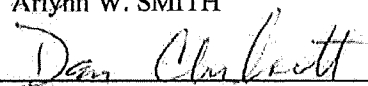
entitled: **METHOD FOR FORMING HERMETIC SEALS IN MEMS DEVICES**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE:  DATE: 11/21/2017  
Arlynn W. SMITH

SIGNATURE:  DATE: 11/21/2017  
Dan CHILCOTT